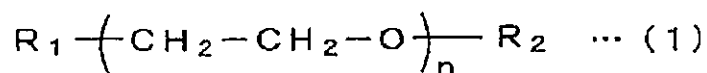


EPOXY RESIN COMPOSITION FOR SEMICONDUCTOR ENCAPSULATION AND SEMICONDUCTOR DEVICE USING THE SAME

ABSTRACT OF THE DISCLOSURE

The present invention relates to an epoxy resin composition for semiconductor encapsulation, including the following components (A) to (E), in which the component (D) is contained in an amount of from 0.1 to 1.5% by weight of the whole of the epoxy resin composition: (A) an epoxy resin; (B) a phenol resin; (C) an inorganic filler; (D) a compound represented by the following formula (1) in which R₁ represents a hydroxyl group or an alkoxy group, R₂ represents a hydrogen atom or a monovalent hydrocarbon group, and n is an integer of from 1 to 7; and (E) a release agent including at least one of the following (α) and (β): (α) a linear saturated carboxylic acid having a number average molecular weight of from 550 to 800, and (β) an oxidized polyethylene wax:



NO SUITABLE FIGURE